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Responsible committee: EPL/501 Electronic assembly technology

Interested committees:

Title: Draft BS EN 62588 ED.1 Marking and labeling components, PCBs and PCBAs to identify lead (Pb), lead-free (Pb-free) and other attributes

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- iii) requires additional national guidance or information

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Introduction

This draft standard is based on international discussions in which the UK has taken an active part. Your comments on this draft are welcome and will assist in the preparation of the consequent standard. There is a high probability that this text could be adopted by CENELEC as a reference document for harmonization or as a European Standard. Recipients of this draft are requested to comment on the text bearing in mind this possibility.

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Template for comments and secretariat observations

Date: xx/xx/20xx	Document: ISO/DIS xxxx
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1	2	(3)	4	5	(6)	(7)
MB	Clause No./ Subclause No./Annex (e.g. 3.1)	Paragraph/ Figure/ Table/Note	Type of comment	Commend (justification for change) by the MB	Proposed change by the MB	Secretariat observations on each comment submitted
	3.1	Definition 1	ed	Definition is ambiguous and needs clarifying.	Amend to read '...so that the mains connector to which no connection...'	
	6.4	Paragraph 2	te	The use of the UV photometer as an alternative cannot be supported as serious problems have been encountered in its use in the UK.	Delete reference to UV photometer.	



91/1036/CD

COMMITTEE DRAFT (CD)

IEC/TC or SC: TC 91		Project number IEC 62588 Ed.1	
Title of TC/SC: Electronics assembly technology		Date of circulation 2012-03-30	Closing date for comments 2012-07-06
Also of interest to the following committees SC 3C, TC 111		Supersedes document 91/979/NP, 91/1018/RVN	
Proposed horizontal standard ☐ Other TC/SCs are requested to indicate their interest, if any, in this CD to the TC/SC secretary			
Functions concerned: ☐ Safety ☐ EMC ☐ Environment ☒ Quality assurance			
Secretary: Kazuhiko MAEJIMA		THIS DOCUMENT IS STILL UNDER STUDY AND SUBJECT TO CHANGE. IT SHOULD NOT BE USED FOR REFERENCE PURPOSES. RECIPIENTS OF THIS DOCUMENT ARE INVITED TO SUBMIT, WITH THEIR COMMENTS, NOTIFICATION OF ANY RELEVANT PATENT RIGHTS OF WHICH THEY ARE AWARE AND TO PROVIDE SUPPORTING DOCUMENTATION.	

Title:
Marking and Labeling of Components, PCBs and PCBAs to identify lead (Pb), lead-free (Pb-free) and other attributes

(Titre) :

Introductory note

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

Marking and labeling of components, PCBs and PCBA's to identify lead (Pb), lead-free (Pb-free) and other attributes

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International Standard IEC 62588 Ed. 1.0 has been prepared by IEC technical committee 91: Electronics assembly technology.

The text of this standard is based on the following documents:

FDIS	Report on voting
91/XX/FDIS	91/XX/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

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